

**PS7341C-1A, PS7341CL-1A****CURRENT LIMIT TYPE  
6-PIN DIP, HIGH ISOLATION VOLTAGE  
1-ch Optical Coupled MOS FET****DESCRIPTION**

The PS7341C-1A and PS7341CL-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs including current control circuit on the output side. Current control circuit of OCMOS FET protects this device from thermal breakdown and output circuit.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7341CL-1A has a surface mount type lead.

**★ FEATURES**

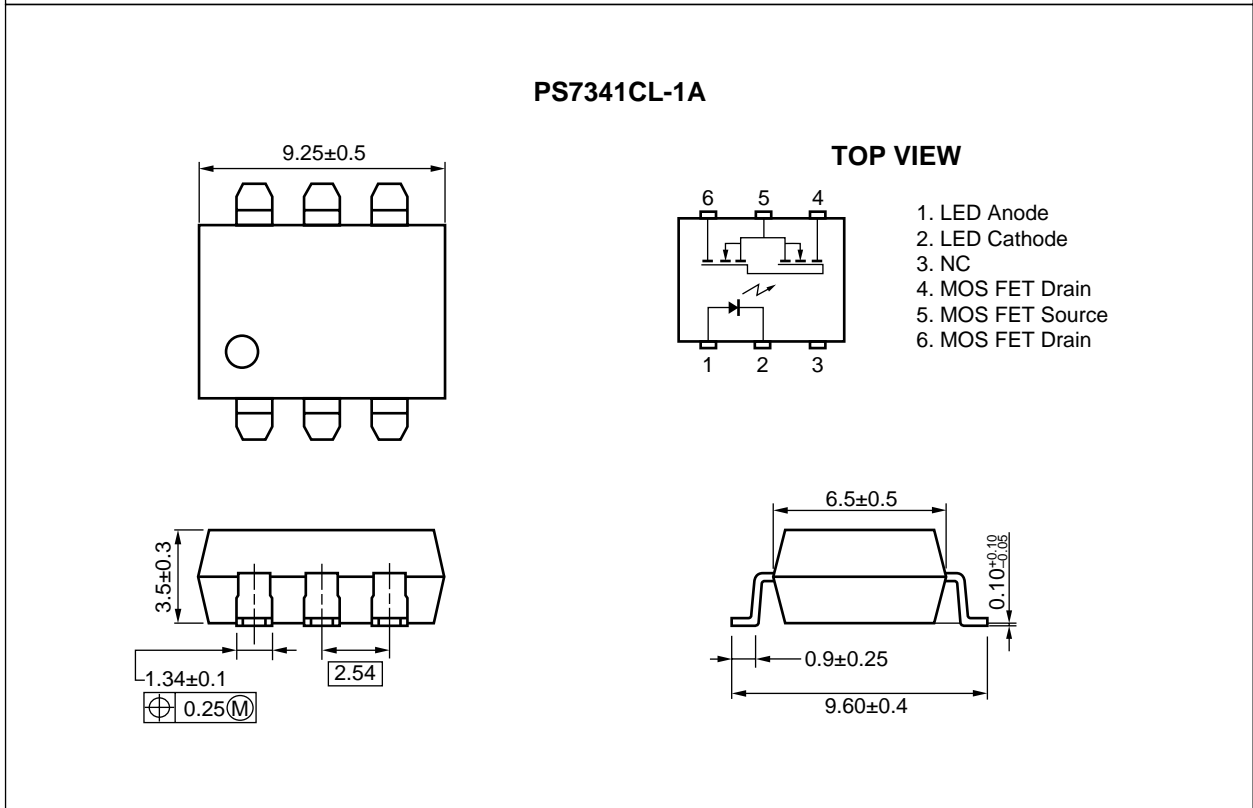
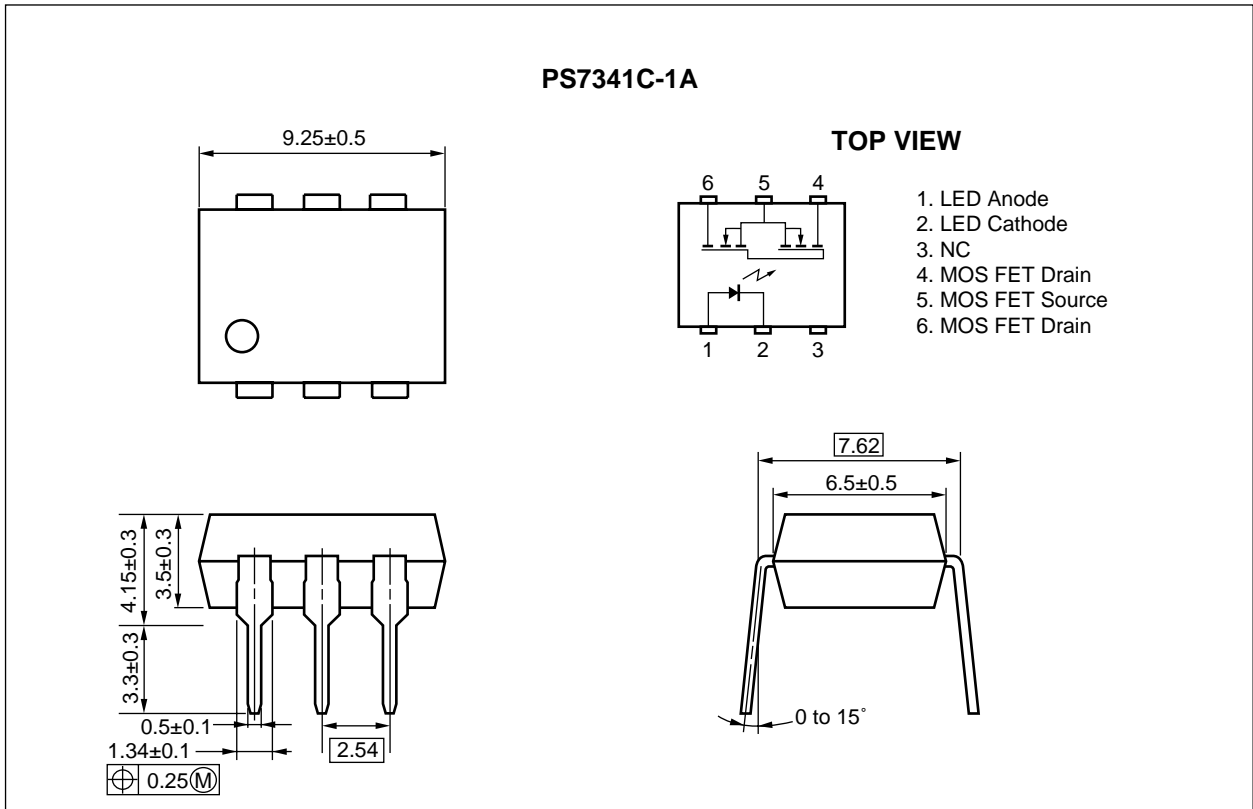
- Limit current ( $I_{LMT} = 125$  to  $250$  mA)
- High isolation voltage ( $BV = 3\ 750$  Vr.m.s.)
- 1 channel type (1 a output)
- Low LED operating current ( $I_F = 2$  mA)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS7341CL-1A: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8252/8253
- CSA approved: No. CA 101391

**APPLICATIONS**

- Exchange equipment
- Measurement equipment
- FA/OA equipment

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

PACKAGE DIMENSIONS (in millimeters)



★ **ORDERING INFORMATION**

Part Number	Package	Packing Style	Application Part Number <sup>*1</sup>
PS7341C-1A	6-pin DIP	Magazine case 50 pcs	PS7341C-1A
PS7341CL-1A			PS7341CL-1A
PS7341CL-1A-E3		Embossed Tape 1 000 pcs/reel	
PS7341CL-1A-E4			

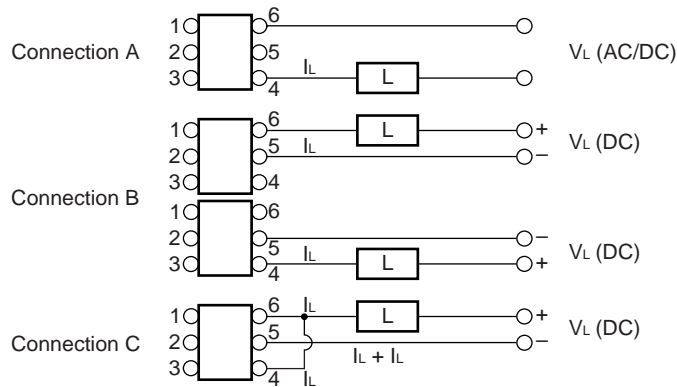
\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	I <sub>F</sub>	50	mA	
	Reverse Voltage	V <sub>R</sub>	5.0	V	
	Power Dissipation	P <sub>D</sub>	50	mW	
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	1	A	
MOS FET	Break Down Voltage	V <sub>L</sub>	400	V	
	Continuous Load Current <sup>*2</sup>	Connection A	I <sub>L</sub>	120	mA
		Connection B		120	
		Connection C		240	
	Pulse Load Current <sup>*3</sup> (AC/DC Connection)	I <sub>LP</sub>	120	mA	
Power Dissipation	P <sub>D</sub>	560	mW		
Isolation Voltage <sup>*4</sup>		BV	3 750	V <sub>r.m.s.</sub>	
Total Power Dissipation		P <sub>T</sub>	610	mW	
Operating Ambient Temperature		T <sub>A</sub>	-40 to +85	°C	
Storage Temperature		T <sub>stg</sub>	-40 to +125	°C	

\*1 PW = 100 μs, Duty Cycle = 1 %

\*2 Conditions: I<sub>F</sub> ≥ 2 mA. The following types of load connections are available.



\*3 PW = 100 ms, 1 shot

\*4 AC voltage for 1 minute at T<sub>A</sub> = 25 °C, RH = 60 % between input and output

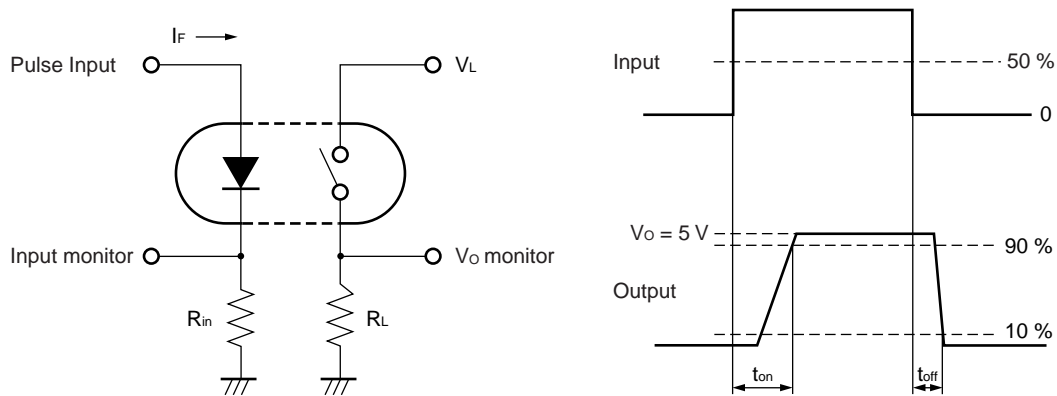
RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I <sub>F</sub>	2	10	20	mA
LED Off Voltage	V <sub>F</sub>	0		0.5	V

★ ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA		1.2	1.4	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I <sub>Loff</sub>	V <sub>D</sub> = 400 V		0.001	1.0	μA
	Output Capacitance	C <sub>out</sub>	V <sub>D</sub> = 0 V, f = 1 MHz		63		pF
Coupled	LED On-state Current	I <sub>Fon</sub>	I <sub>L</sub> = 120 mA			2.0	mA
	On-state Resistance	R <sub>on1</sub>	I <sub>F</sub> = 10 mA, I <sub>L</sub> = 10 mA		27	35	Ω
		R <sub>on2</sub>	I <sub>F</sub> = 10 mA, I <sub>L</sub> = 120 mA, t ≤ 10 ms		22	30	
	Turn-on Time <sup>*1</sup>	t <sub>on</sub>	I <sub>F</sub> = 10 mA, V <sub>O</sub> = 5 V, PW ≥ 10 ms		0.55	1.0	ms
	Turn-off Time <sup>*1</sup>	t <sub>off</sub>			0.07	1.0	
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1.0 kV <sub>DC</sub>	10 <sup>9</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		1.1		pF
Limit Current <sup>*2</sup>	I <sub>LMT</sub>	I <sub>F</sub> = 10 mA, t = 5 ms, V <sub>L</sub> = 6 V	125	200	250	mA	

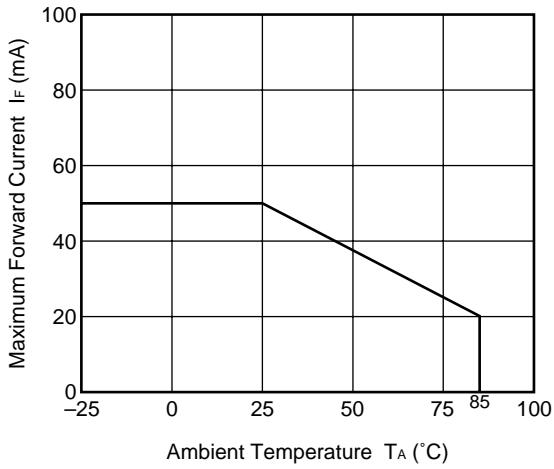
\*1 Test Circuit for Switching Time



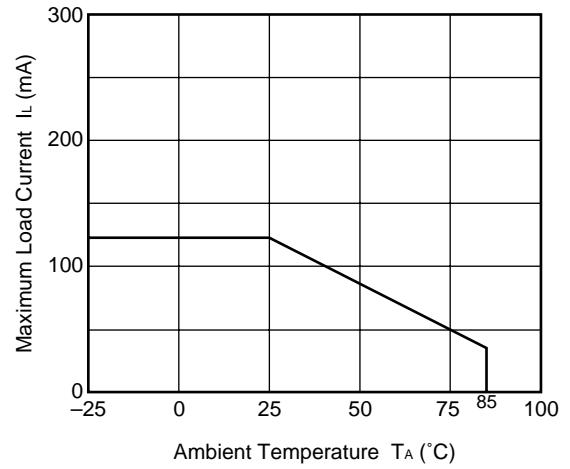
- \*2 N rank : 125 to 250 mA
- M rank : 125 to 180 mA
- L rank : 170 to 250 mA

★ TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise specified)

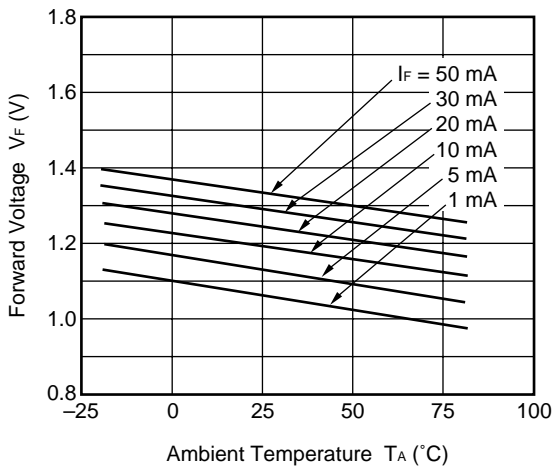
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



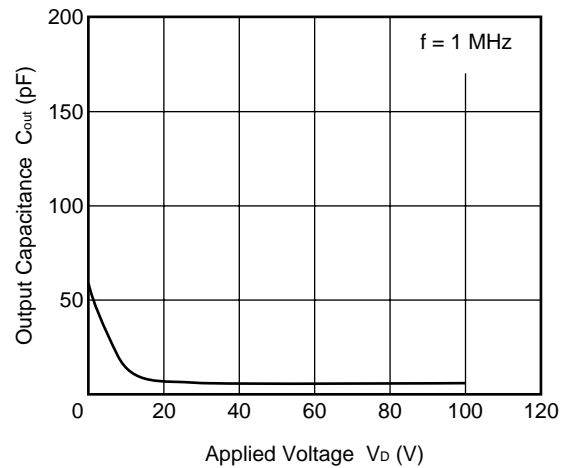
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



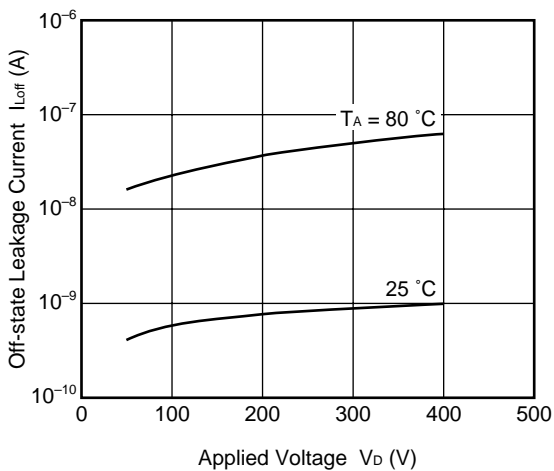
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



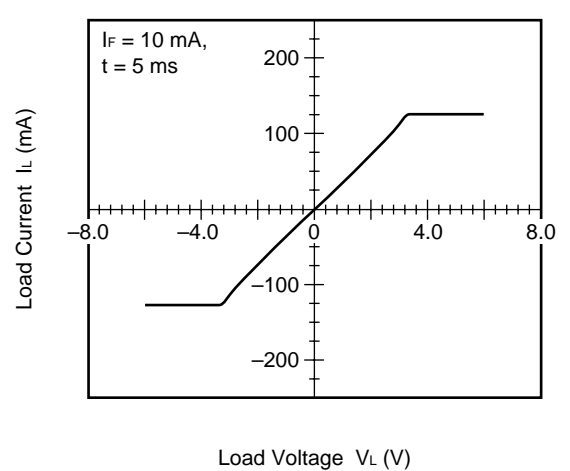
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



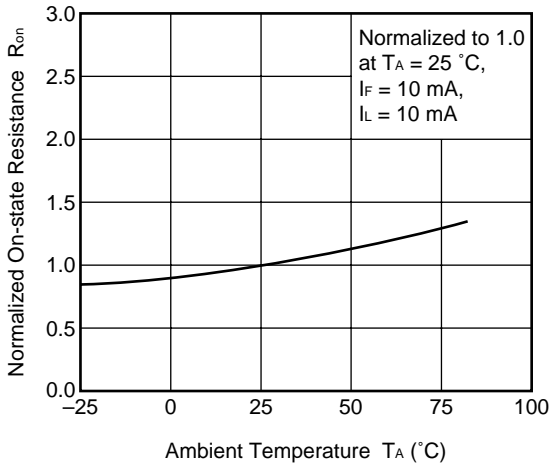
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



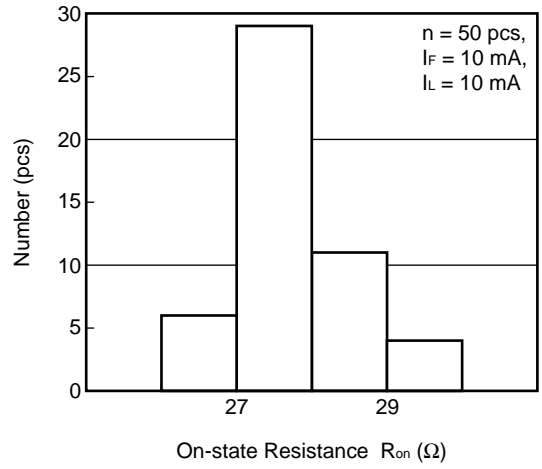
LOAD CURRENT vs. LOAD VOLTAGE



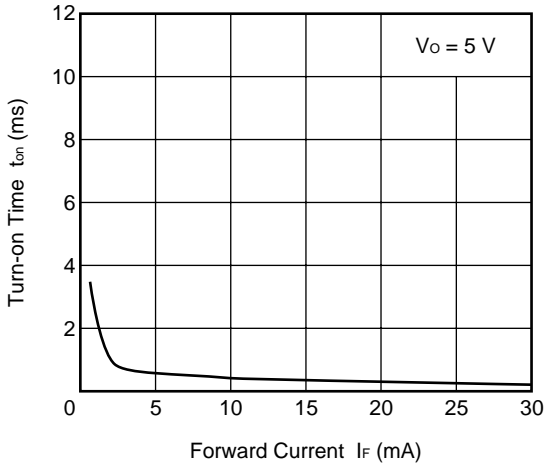
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



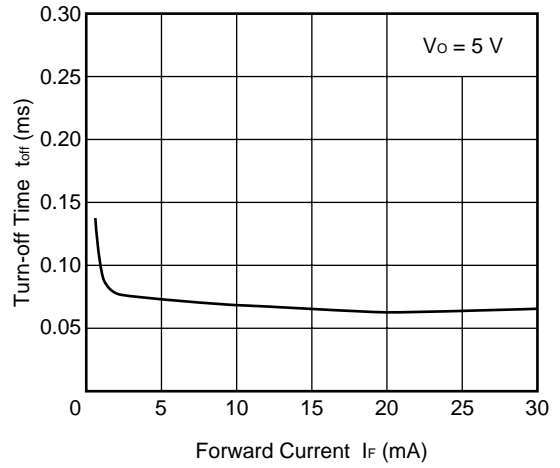
ON-STATE RESISTANCE DISTRIBUTION



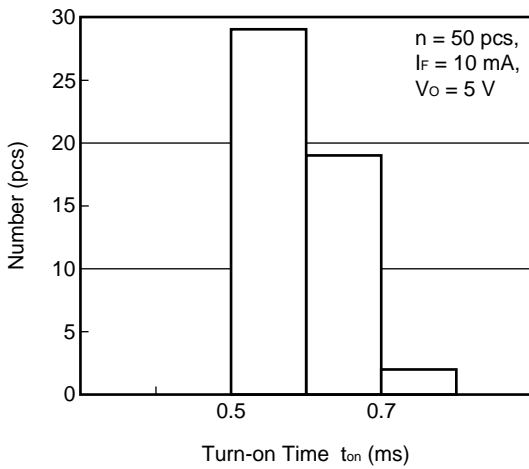
TURN-ON TIME vs. FORWARD CURRENT



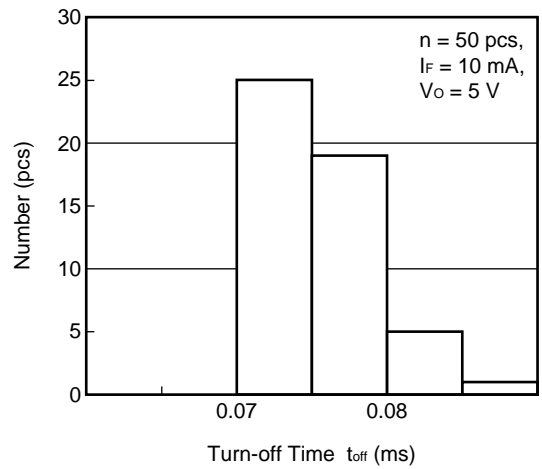
TURN-OFF TIME vs. FORWARD CURRENT



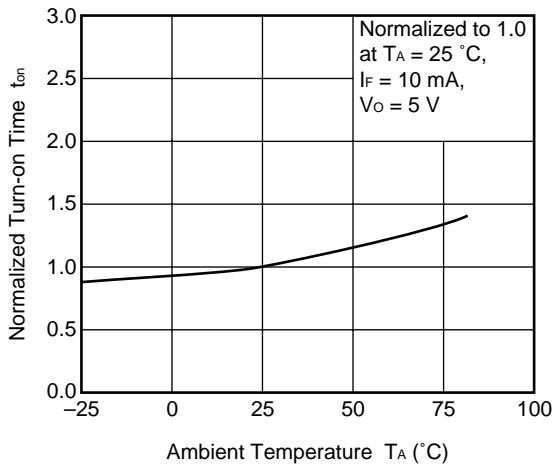
TURN-ON TIME DISTRIBUTION



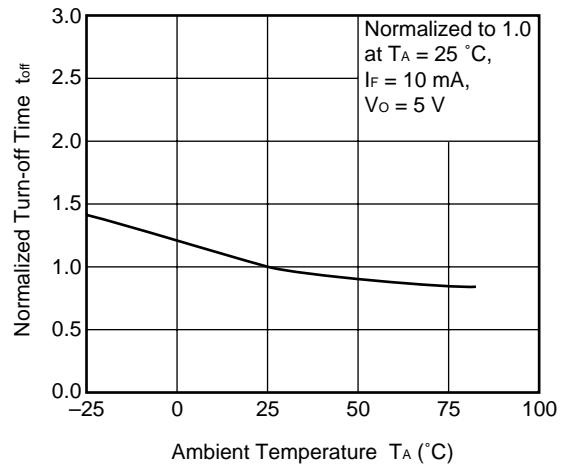
TURN-OFF TIME DISTRIBUTION



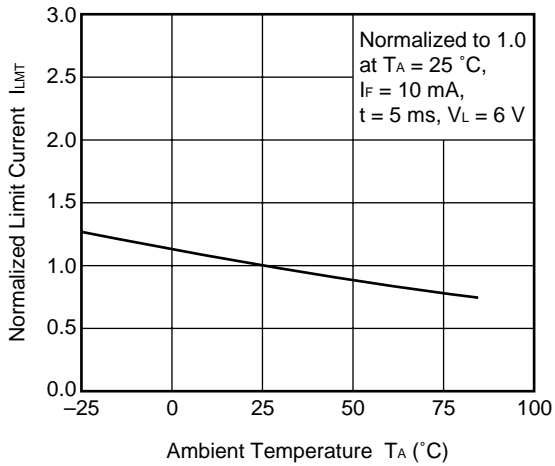
NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



NORMALIZED LIMIT CURRENT vs. AMBIENT TEMPERATURE

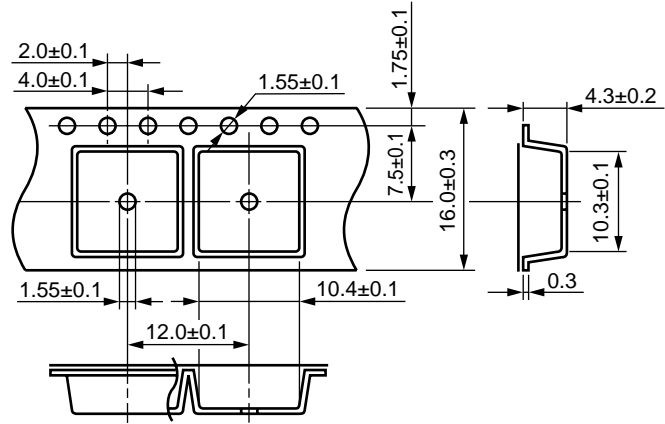


**Remark** The graphs indicate nominal characteristics.

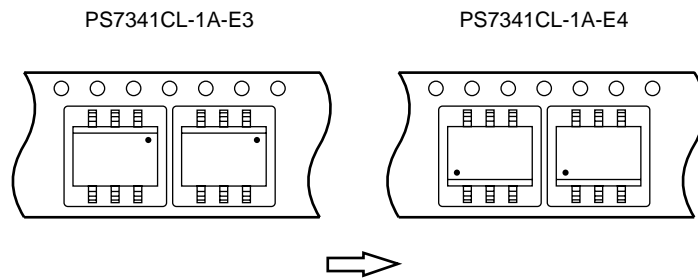


★ TAPING SPECIFICATIONS (in millimeters)

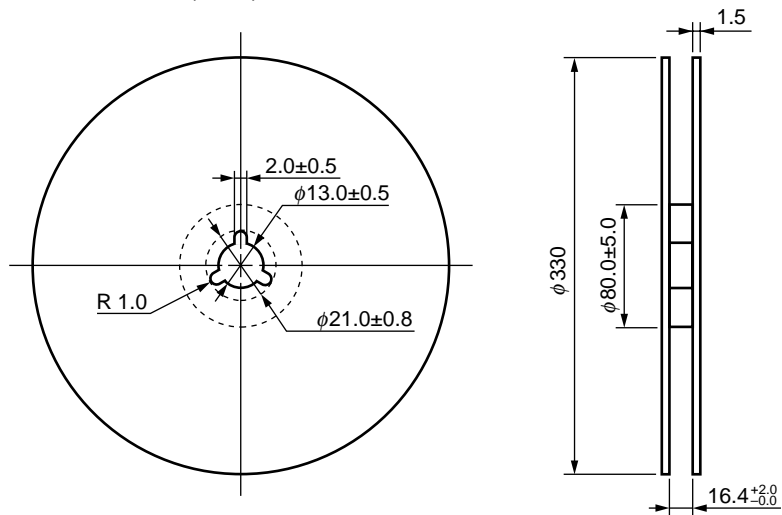
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

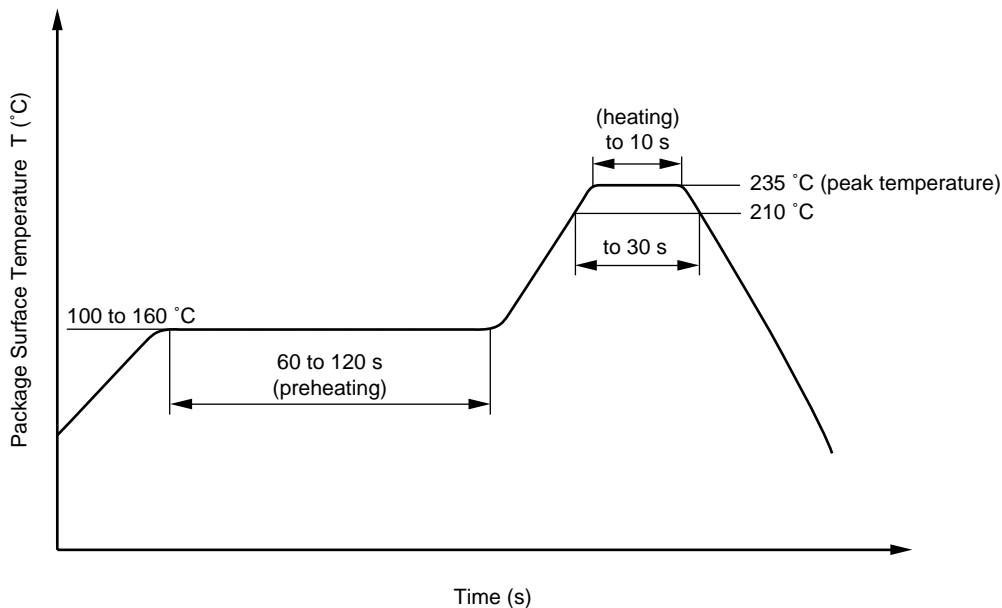
**RECOMMENDED SOLDERING CONDITIONS**

**(1) Infrared reflow soldering**

- Peak reflow temperature 235 °C (package surface temperature)
- Time of temperature higher than 210 °C 30 seconds or less
- Number of reflows One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

★

Recommended Temperature Profile of Infrared Reflow



**(2) Dip soldering**

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

**(3) Cautions**

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Products in dry pack  
After opening the dry pack, solder the products within the valid storage period specified on the label on the dry pack.

[MEMO]

**CAUTION**

**Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.**

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